

1 1. A socket comprising:
2 an upper surface with a plurality of solder ball
3 receiving apertures formed therein; and
4 a plurality of S-shaped spring contacts aligned
5 with said apertures to electrically engage a solder ball
6 inserted into an aperture.

1 2. The socket of claim 1 wherein said spring
2 contacts to make wiping electrical contact with solder
3 balls.

1 3. The socket of claim 1 wherein said spring
2 contacts to make wiping electrical contact with lands.

1 4. The socket of claim 1 wherein said S-shaped
2 spring contacts include opposed contact arms, one of which
3 extends upwardly and the other which extends downwardly.

1 5. The socket of claim 1 wherein socket includes a
2 body, said body having said apertures formed therein.

1 6. The socket of claim 5 including an alignment
2 feature extending upwardly from said body to align a land
3 grid array package with said socket.

1 7. The socket of claim 1 wherein said spring
2 contacts include an upwardly extending arm to make contact
3 with an integrated circuit package and a downwardly
4 extending arm to make contact with an underlying circuit
5 board.

1 8. The socket of claim 1 wherein said socket
2 includes a body including an upwardly extending protrusion,
3 said protrusion having a height less than the height of a
4 solder ball for a ball grid array package.

1 9. The socket of claim 8 wherein said alignment
2 feature is L-shaped.

1 10. The socket of claim 9 including two L-shaped
2 alignment features opposed diagonally from one another on
3 said socket.

1 11. An electronic device comprising:
2 a printed circuit board;
3 a socket coupled to said printed circuit board,
4 said socket including a housing having an upper surface
5 with a plurality of solder ball receiving apertures formed
6 therein and a plurality of spring contacts aligned with
7 said apertures to electrically engage a solder ball
8 inserted into an aperture.

1 12. The device of claim 11 wherein said contacts are
2 S-shaped spring contacts.

1 13. The device of claim 12 wherein said spring
2 contacts include opposed contact arms, one of which extends
3 upwardly and the other which extends downwardly to contact
4 said printed circuit board.

1 14. The device of claim 13 wherein said printed
2 circuit board has lands engaged by said spring contacts.

1 15. The device of claim 11 wherein said housing
2 includes a protrusion on its upper surface to align a land
3 grid array package with said housing.

1 16. The device of claim 15 wherein said alignment
2 feature is L-shaped.

1 17. The device of claim 16 including two L-shaped
2 alignment features opposed diagonally from one another on
3 said housing.

1 18. The device of claim 11 including a ball grid
2 array package engaged on said socket housing.

1 19. The device of claim 11 including a land grid
2 array package engaged on said socket housing.